



## Material Content Data Sheet



<b>Sales Product Name</b>				BSZ340N08NS3 G		<b>Issued</b>		22. January 2018	
<b>MA#</b>				MA001313680					
<b>Package</b>				PG-TSDSON-8-1		<b>Weight*</b>		36.14 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.830	2.30	2.30	22961	22961	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		65		
	non noble metal	zinc	7440-66-6	0.009	0.03		262		
	non noble metal	iron	7439-89-6	0.189	0.52		5239		
wire	non noble metal	copper	7440-50-8	7.689	21.27	21.83	212744	218310	
	non noble metal	copper	7440-50-8	0.040	0.11	0.11	1101	1101	
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		1030	
	plastics	epoxy resin	-	1.918	5.31		53071		
	inorganic material	silicondioxide	60676-86-0	16.667	46.13	51.54	461150	515251	
leadfinish	non noble metal	tin	7440-31-5	0.370	1.02	1.02	10239	10239	
plating	noble metal	silver	7440-22-4	0.081	0.22	0.22	2236	2236	
solder	noble metal	silver	7440-22-4	0.028	0.08		780		
	non noble metal	tin	7440-31-5	0.023	0.06		624		
	non noble metal	lead	7439-92-1	1.078	2.98	3.12	29814	31218	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		33		
	non noble metal	zinc	7440-66-6	0.005	0.01		130		
	non noble metal	iron	7439-89-6	0.094	0.26		2600		
heat sink CLIP	non noble metal	copper	7440-50-8	3.816	10.56	10.83	105582	108345	
	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	zinc	7440-66-6	0.004	0.01		108		
	non noble metal	iron	7439-89-6	0.078	0.22		2168		
	non noble metal	copper	7440-50-8	3.182	8.80	9.03	88036	90339	
*deviation	< 10%		Sum in total:			100.00		1000000	

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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